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(54) Title: RESIN MORTARS FOR CHEMICAL FASTENING

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(57) Abstract: The invention relates to radically curable resin mortars, containing unsaturated polyester and a reactive diluent, for use as A-component in two-component (+B-component containing peroxide and possibly an extender) for chemical fastening systems, wherein the diluent in the A-component is either a monomeric component according to formula (1) (A-CH=CH-O)_n-R₀ or a resinous compound comprising, in a covalently built-in manner, a monomeric component having vinyl ether group(s), and the content of the component containing one or more vinyl ether group(s) being from 0.5 to 50 wt.%, calculated (as indicated) as weight percentage relative to the resin composition. A, R and n are specified as hydrogen or C₁₋₃alkyl; C₁₋₂₀(hereto)-aliphatic with hydroxyl or amino groups, or poly(C₂₀₋₃)glycol with 2-120 glycol units; and 1 to 4, respectively. The resinous compounds with built-in vinyl ether group(s) (0.5 to 50 wt.%, calculated as indicated) are obtained by reaction of a mixture of appropriate amounts of: a) a first compound (HVE) containing hydroxyl group(s) and at least one vinyl ether group, and b) a second compound (D/HIC), being an isocyanate; and c) a third compound (G/P/HP) from (1) C₂₋₆glycols, (2) C₅₋₂₀polyols having 2-5 hydroxyl groups and (3) hydroxyl terminated polyester compounds, not being alkyd resins, having 1-5 free hydroxyl groups and 2-50 monomeric units, or mixtures thereof. The invention also relates to two-component chemical fastening systems comprising such curable mortar and B-component, as well as to methods of preparing such mortars and use thereof for chemical fastening.